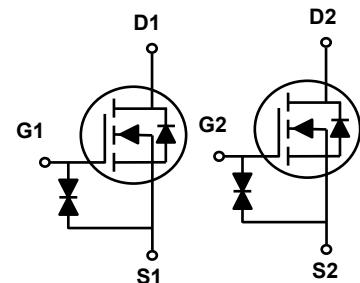
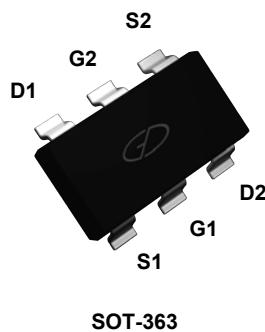


## Main Product Characteristics

$V_{DS}$	30V
$R_{DS(ON)}$	450mΩ
$I_D$	800mA



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switch mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFK0300 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	800	mA
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		510	mA
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	3.2	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	275	mW
Power Dissipation-Derate Above 25°C		2.2	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	450	°C/W
Storage Temperature Range	$T_{STG}$	-55 To +150	°C
Operating Junction Temperature Range	$T_J$	-55 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	-0.01	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 20$	$\mu\text{A}$
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.5	0.7	1.2	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	-1.74	-	$\text{mV}/^\circ\text{C}$
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.3\text{A}$	-	370	450	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=0.2\text{A}$	-	510	650	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=4\text{V}, I_{\text{D}}=0.3\text{A}$	-	0.8	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	72.9	146	PF
Output Capacitance	$C_{\text{oss}}$		-	18.3	36.6	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	7.4	14.8	
Turn-On Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=0.3\text{A}$ $V_{\text{GS}}=4.5\text{V}, R_{\text{G}}=10\Omega$	-	5.5	11	nS
Rise Time <sup>2,3</sup>	$t_{\text{r}}$		-	4	8	
Turn-Off Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{off})}$		-	14.5	29	
Fall Time <sup>2,3</sup>	$t_{\text{f}}$		-	6.5	13	
Total Gate Charge <sup>2,3</sup>	$Q_{\text{g}}$	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=0.3\text{A}, V_{\text{GS}}=4.5\text{V}$	-	2.6	5.2	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	0.9	1.8	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	0.6	1.2	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=0.3\text{A}, T_J=25^\circ\text{C}$	-	-	1	V
Continuous Source Current	$I_{\text{s}}$	$V_{\text{G}}=V_{\text{D}}=0\text{V}$ , Force Current	-	-	0.78	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	1.56	A

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. Pulse test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

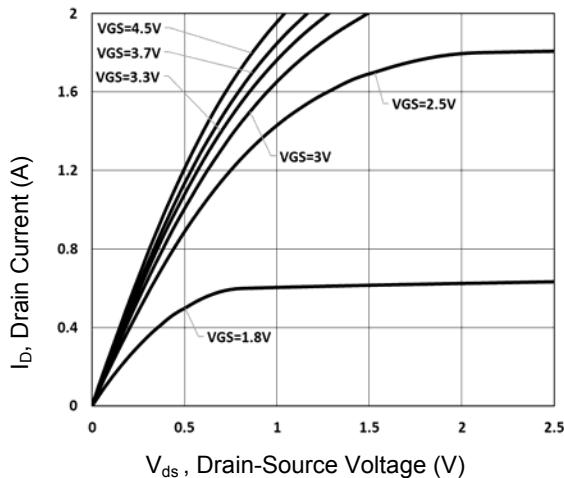


Figure 1. Typical Output Characteristics

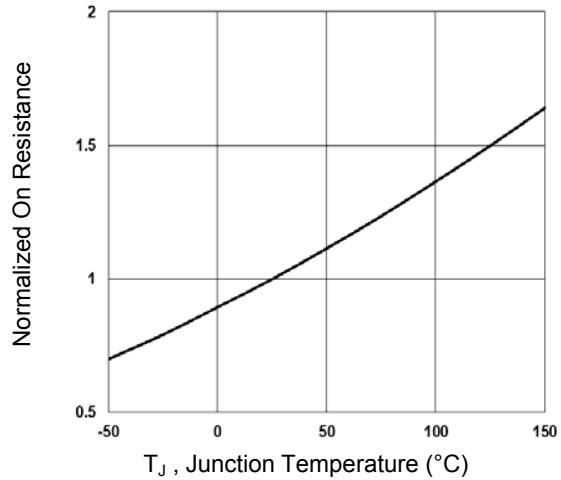


Figure 2. Normalized  $R_{DS(ON)}$  vs.  $T_J$

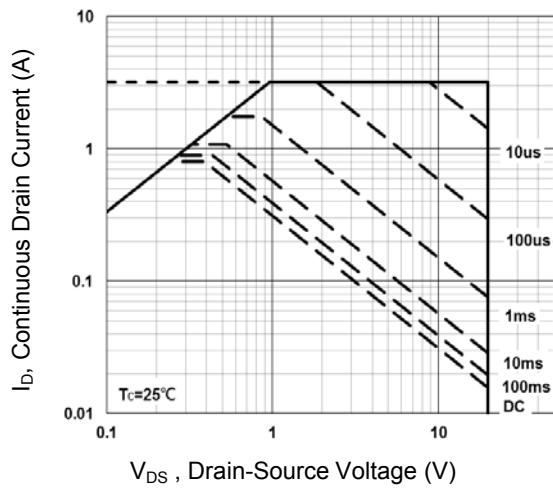


Figure 3. Maximum Safe Operation Area

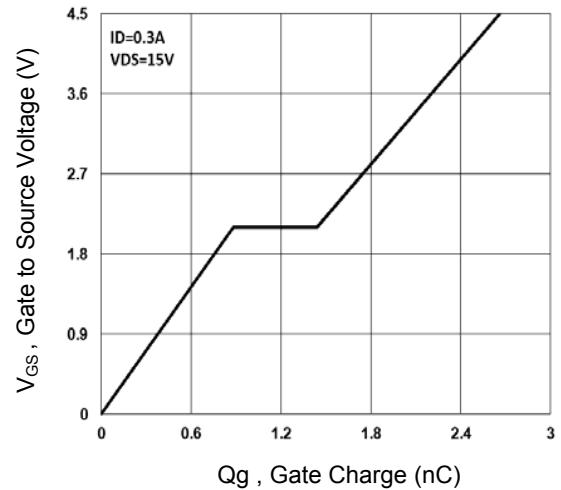


Figure 4. Gate Charge Waveform

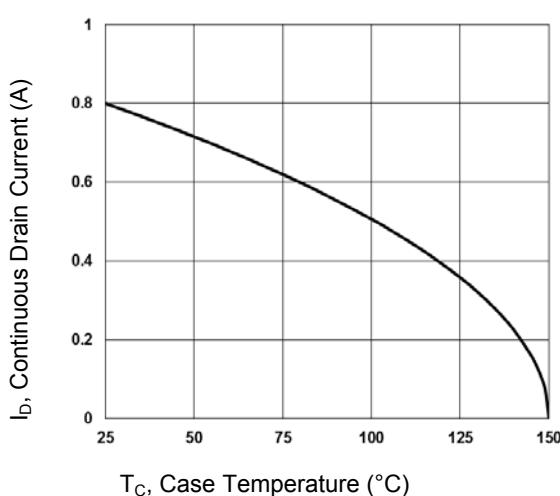


Figure 5. Continuous Drain Current vs.  $T_c$

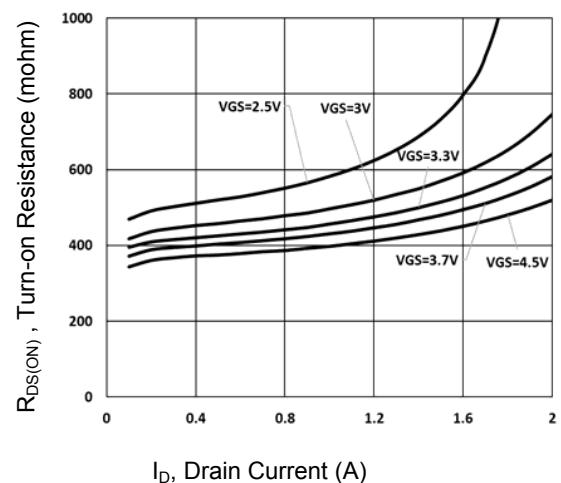


Figure 6. Turn-On Resistance vs.  $I_D$

### Typical Electrical and Thermal Characteristic Curves

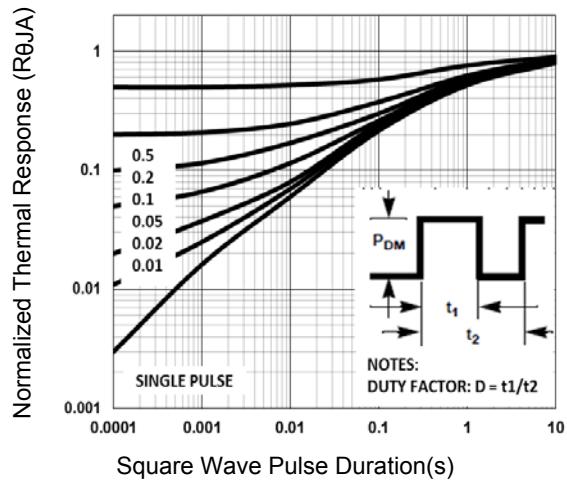


Figure 7. Normalized Transient Impedance

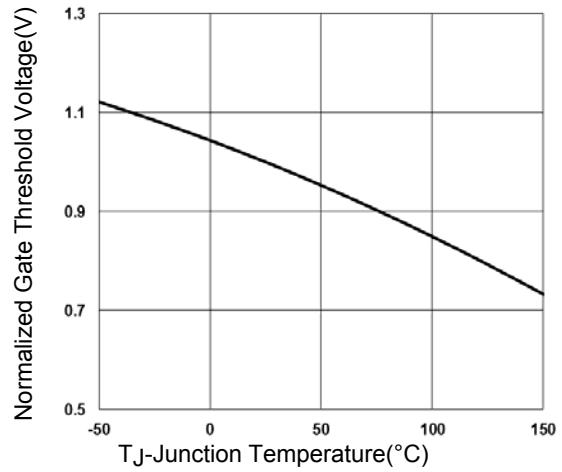
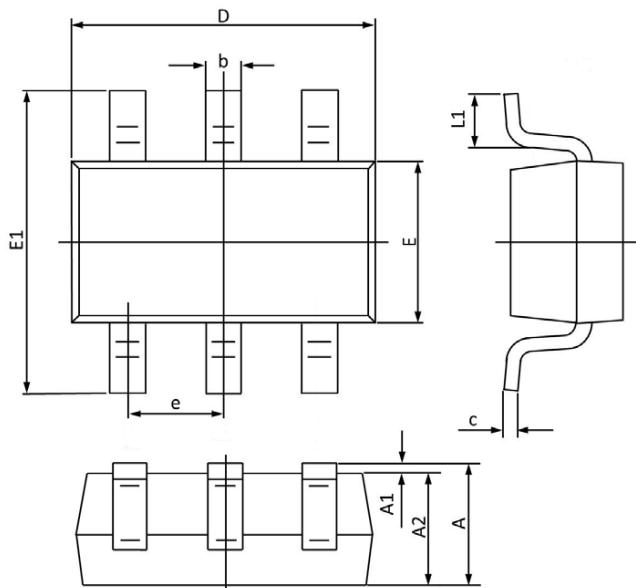


Figure 8. Normalized  $V_{th}$  VS  $T_J$

### Package Outline Dimensions (SOT-363)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
A1	0.100	0.000	0.004	0.000
A2	1.000	0.800	0.039	0.031
b	0.330	0.100	0.013	0.004
c	0.250	0.100	0.010	0.004
D	2.200	1.800	0.087	0.071
E	1.350	1.150	0.053	0.045
E1	2.400	1.800	0.094	0.071
e	0.65BSC		0.026BSC	
L1	0.350	0.100	0.014	0.004

### Order Information

Device	Package	Marking Code	Carrier	Quantity	HSF Status
GSFK0300	SOT-363	U	Tape & Reel	3000/Reel	RoHS Compliant